

P-Channel Enhancement Mode MOSFET

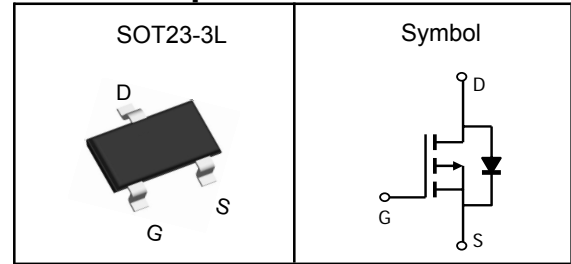
Features

- Low Rdson for low conduction loss
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

Applications

- Power Management in Desktop Computer
- DC/DC Converters

Pin Description



V _{bss}	-20	V
R _{DS(ON)-Typ}	25	mΩ
I _D	-6	A

Absolute Maximum Ratings (T_J=25°C, Unless Otherwise Noted)

Symbol	Parameter	N-Channel	Unit
V _{bss}	Drain-Source Voltage	-20	V
V _{GSS}	Gate-Source Voltage	±12	V
T _J	Maximum Junction Temperature	-55 to 150	°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
I _{DM} ^①	Pulse Drain Current Tested	T _c =25°C -24	A
I _D	Continuous Drain Current	T _c =25°C -6	A
P _D	Maximum Power Dissipation	T _c =25°C 1.2	W

Thermal Characteristics

Symbol	Parameter	Rating	Unit
R _{θJA} ^③	Thermal Resistance-Junction to Ambient	100	°C/W

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C.

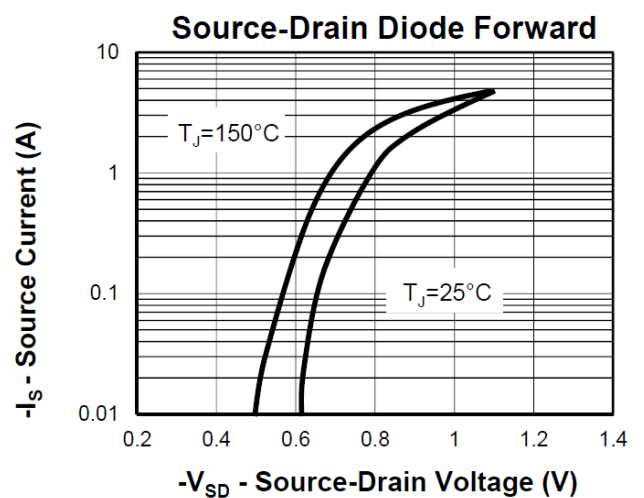
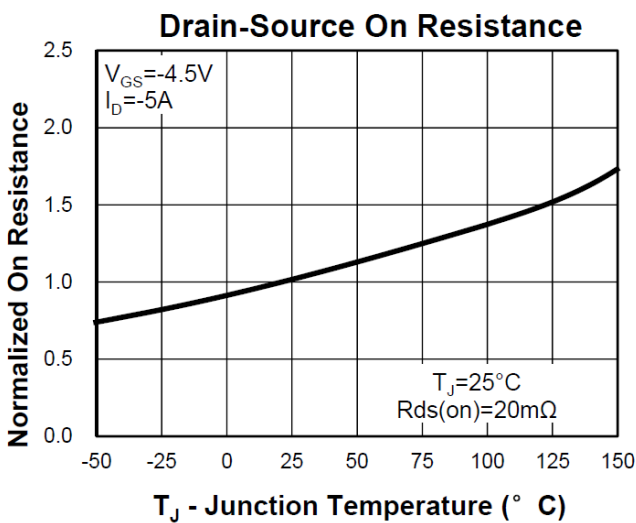
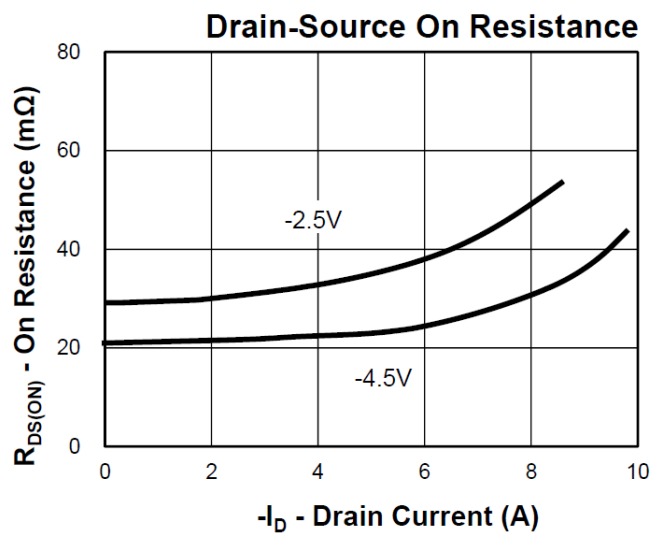
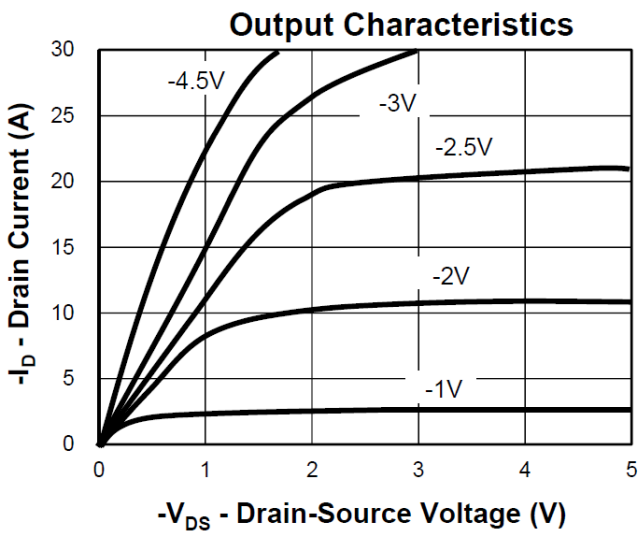
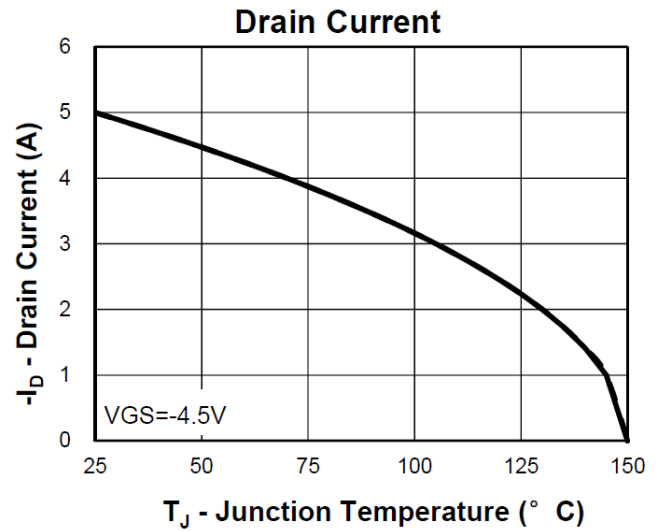
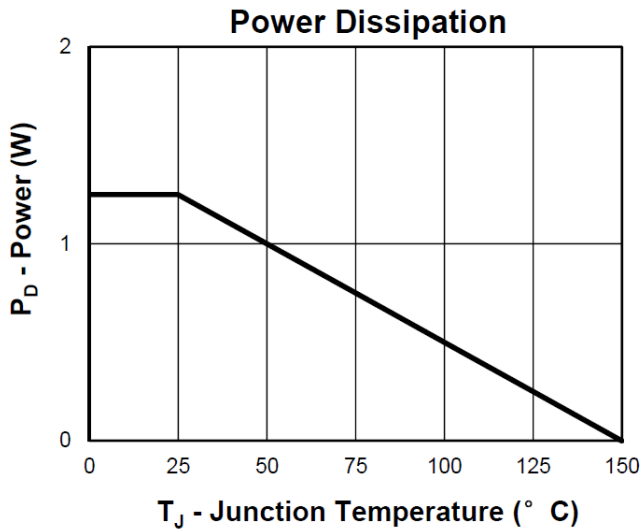
Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

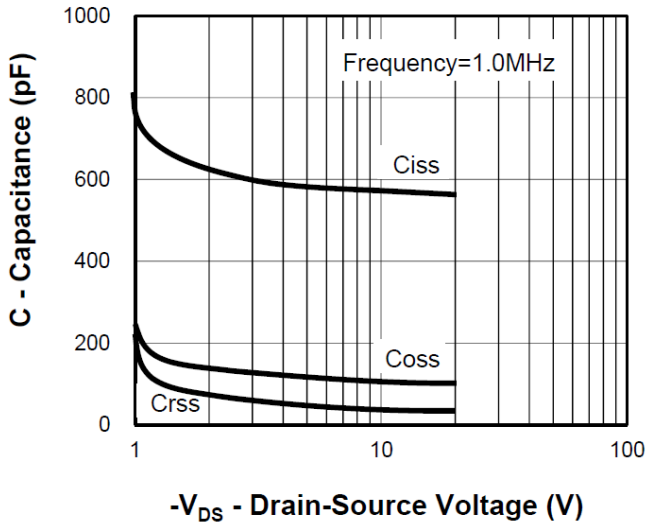
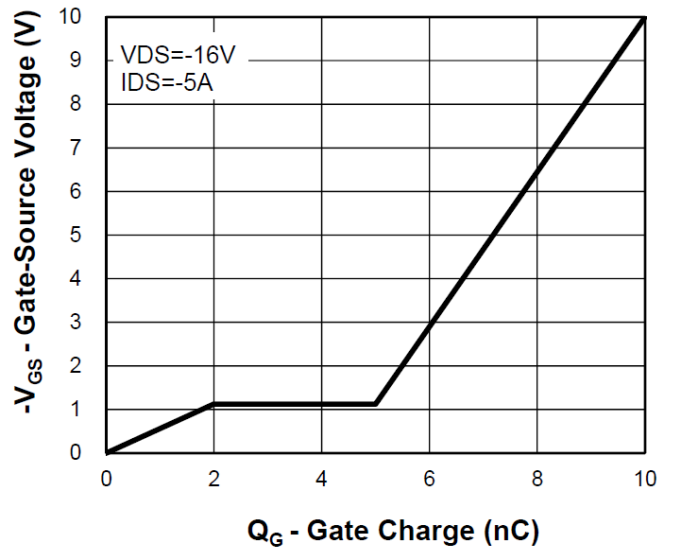
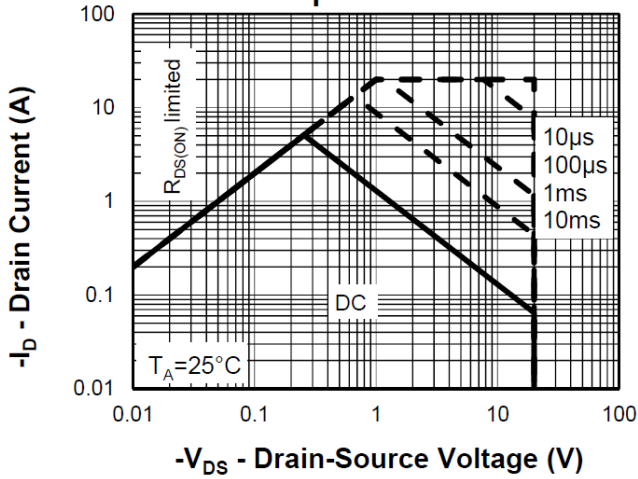
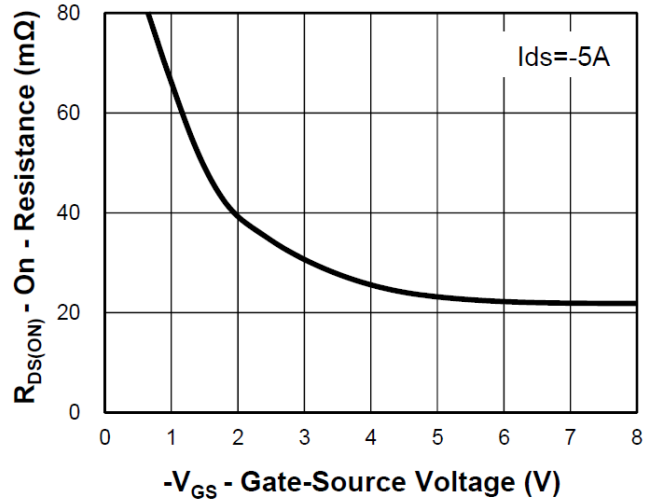
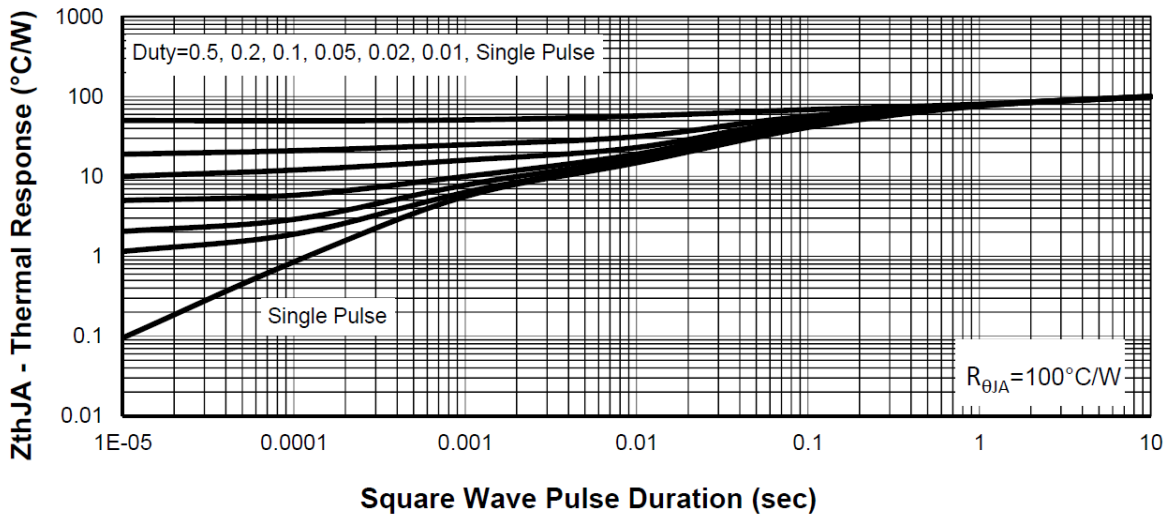
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Electrical Characteristics ($T_J=25^{\circ}\text{C}$, Unless Otherwise Noted)

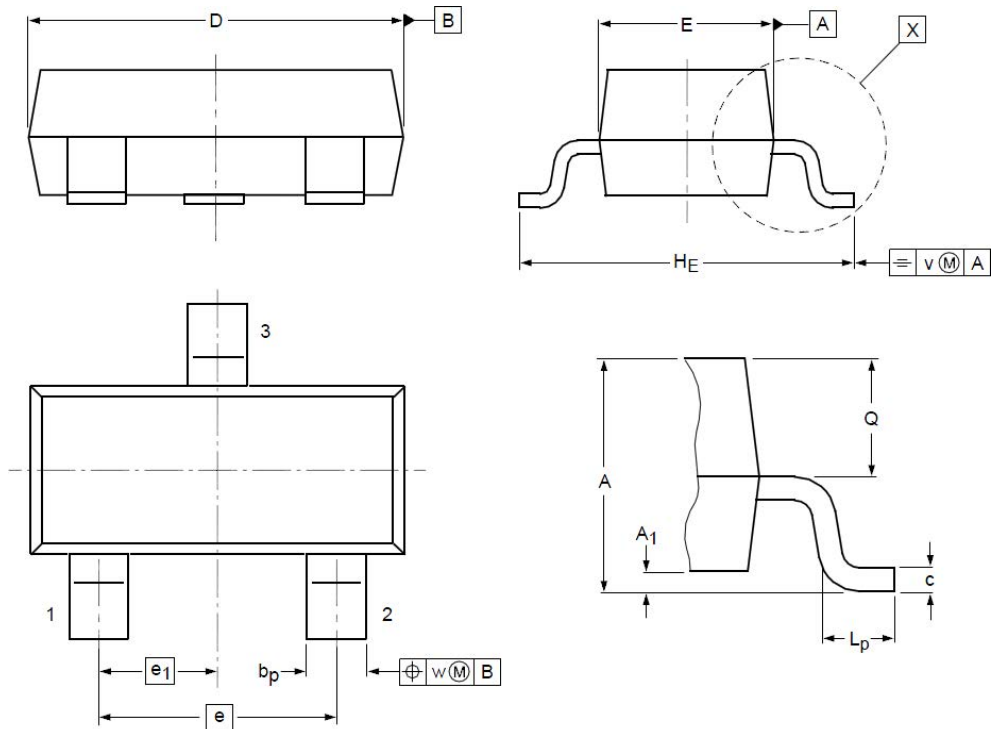
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-20	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-20V, V_{GS}=0V$	---	---	-1	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.5	---	-1.0	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	---	---	± 100	nA
$R_{DS(ON)}$	Drain-Source On-state Resistance	$V_{GS}=-4.5V, I_D=-5A$	---	25	30	m Ω
		$V_{GS}=-2.5V, I_D=-3A$	---	38	45	
gfs	Forward Transconductance	$V_{DS}=-5V, I_D=-6A$	---	5	---	S
Dynamic Characteristics ^⑤						
C_{iss}	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=-10V,$ Freq.=1MHz	---	2100	---	pF
C_{oss}	Output Capacitance		---	498	---	
C_{rss}	Reverse Transfer Capacitance		---	300	---	
$T_{d(on)}$	Turn-on Delay Time	$V_{DD}=-10V, I_D=-2.8A,$ $V_{GS}=-4.5V, R_G=6\Omega,$ $R_L=10\Omega$	---	25	---	nS
T_r	Turn-on Rise Time		---	30	---	
$T_{d(off)}$	Turn-off Delay Time		---	70	---	
T_f	Turn-off Fall Time		---	50	---	
Q_g	Total Gate Charge	$V_{GS}=-10V, V_{DS}=-4.5V,$ $I_D=-6A$	---	17	---	nC
Q_{gs}	Gate-Source Charge		---	4.1	---	
Q_{gd}	Gate-Drain Charge		---	4.3	---	
Source-Drain Characteristics						
V_{SD} ^④	Diode Forward Voltage	$I_S=-1.25A, V_{GS}=0V$	---	-0.81	-1.2	V

Note ④: Pulse test (pulse width 300us, duty cycle 2%).

Note ⑤: Guaranteed by design, not subject to production testing.

P-Channel Enhancement Mode MOSFET
Typical Characteristics


P-Channel Enhancement Mode MOSFET
Capacitance

Gate Charge

Safe Operation Area

Drain Current

Thermal Transient Impedance


P-Channel Enhancement Mode MOSFET
SOT23-3L Package Outline Dimensions


Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	0.90	1.07	1.25	e₁	--	0.95	--
A₁	0.01	0.05	0.10	H_E	2.50	2.80	3.00
b_p	0.30	0.40	0.50	L_p	0.30	0.45	0.60
c	0.10	0.15	0.20	Q	0.23	0.28	0.33
D	2.70	2.90	3.10	V	--	0.20	--
E	1.40	1.55	1.75	W	--	0.20	--
e	--	1.90	--				